

C0805F224K3RACTU

Aliases (C0805F224K3RAC7800) SMD Comm X7R FO, Ceramic, 0.22 uF, 10%, 25 VDC, X7R, SMD, MLCC, Open Mode, Temperature Stable, 0805, 0.7 mm



Click here for the 3D model.

| General Information | |
|--------------------------|---|
| Series | SMD Comm X7R FO |
| Style | SMD Chip |
| Description | SMD, MLCC, Open Mode, Temperature Stable |
| Features | Open Mode, Temperature Stable |
| RoHS | Yes |
| Termination | Tin |
| Marking | No |
| AEC-Q200 | No |
| Typical Component Weight | 13 mg |
| Shelf Life | 78 Weeks |
| MSL | 1 |

| Dimensions | |
|------------|-----------------|
| Chip Size | 0805 |
| L | 2mm +/-0.2mm |
| W | 1.25mm +/-0.2mm |
| т | 0.9mm +/-0.10mm |
| S | 0.7mm MIN |
| В | 0.5mm +/-0.25mm |
| | |

Packaging Specifications

PackagingT&R, 180mm, Paper TapePackaging Quantity4000

| Specifications | |
|--|--|
| Capacitance | 0.22 uF |
| Measurement Condition | 1 kHz 1.0Vrms |
| Tolerance | 10% |
| Voltage DC | 25 VDC |
| Dielectric Withstanding Voltage | 62.5 VDC |
| Temperature Range | -55/+125°C |
| Temp. Coefficient | X7R |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 15%, 1kHz 1.0Vrms |
| Dissipation Factor | 3.5%1kHz1.0Vrms |
| Aging Rate | 3% Loss/Decade Hour: Referee Time is 1000 Hours |
| Insulation Resistance | 2.2727 GOhms |

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